

FIG. 1 (PRIOR ART)

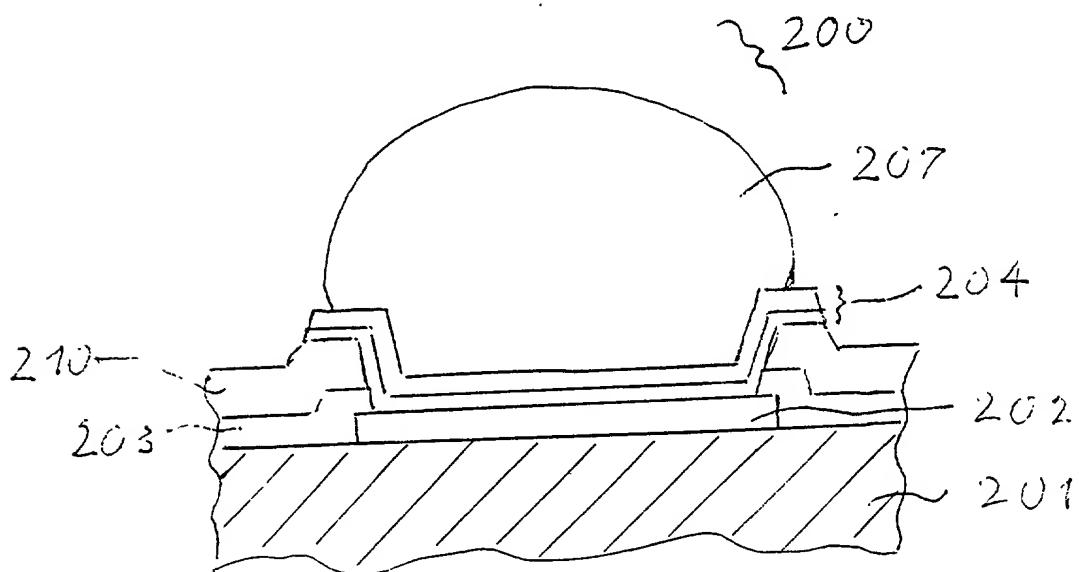


FIG. 2 (PRIOR ART)

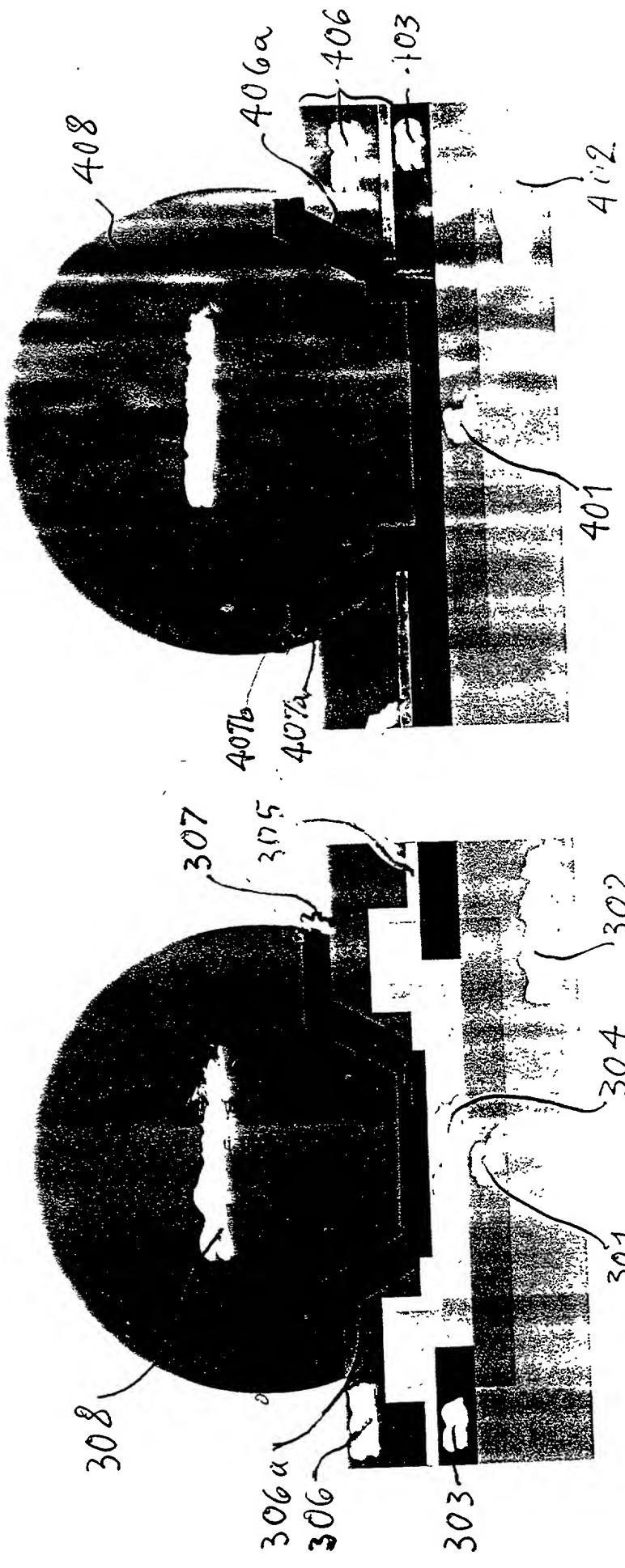


FIG. 3
(PRINTER)
FIG. 4.
(PRIOR ART)

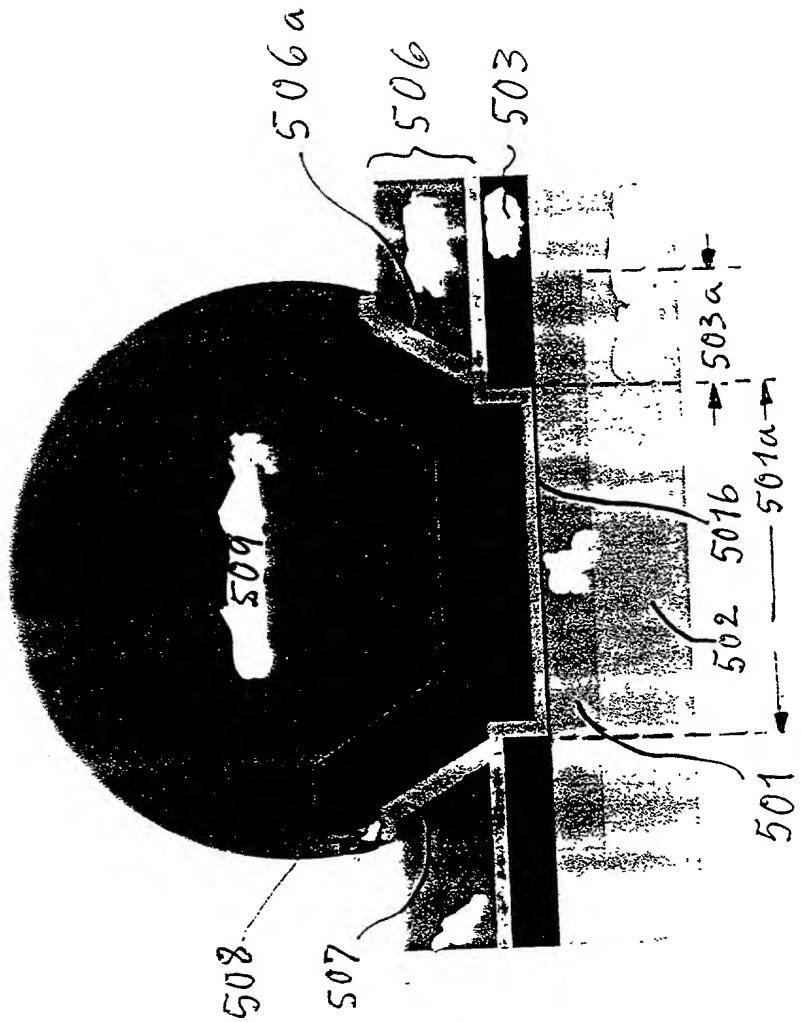


FIG. 5

FIG. 6: Process Flow

for Direct Bumping on Copper Pads

